



26. April 2006

Technical Data Sheet

Product Data SSC: Alloy S-Sn99.3 Cu0.7

GENERAL CHARACTERISTICS

Soldering lead-free binary alloy used in the electronic industry.

- Eutectic alloy containing 0.7% copper with a 227 °C melting point
- Very good mechanical strenght
- Bright alloy
- Very good electrical conductivity
- Lead free

STANDARD: International

Metal: ISO 9453

Flux ISO 9454.1

PHYSICAL AND CHEMICAL CHARACTERISTICS

Copper rate, Cu:	0,45 % to 0,9 %
Tin rate, Sn:	Rest
Melting range:	227 °C – 240 °C
Specific Gravity:	7.3
Temperature:	For iron soldering 315 °C - 370 °C
Mechanical strenght:	Brinell hardness: 14 H.B.
Electric conductance:	14 % IACS
Electrical resistivity:	12 µcm

SUPPLY FORMS

EDSYN GmbH Europa can supply this alloy as:

Wire:	Standard diameters: 0,5 / 0,8 / 1,0 and 1,5 mm
Conditioning standard:	DIN reel of 250 g, 500 g, 1 kg
Solid or flux cored wires:	F-SW 32 No-clean

QUALITY INSURANCE

A certificate of analysis is issued with each delivery of the goods. Quality is assured by using the best materials and one of the most up to date manufacturing process with constant control in production.



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Solder wire with low residues SSC flux according to F-SW32

The flux is made of rosin and of various active agents halid free and carefully selected for their non corrosive power.

Acidity value: 520
Cores: 5

The result is in a regular and clean soldered surface, where cleaning of printed circuit boards is not necessary, giving reduction of cost production.

SSC solder wire can be made with different alloys.

Sn 99.3 Cu 0.7

See alloy technical data sheet.

Tip temperature:

Recommended: 315°C
Maximum: 370°C

Soldering applications: tinned or coppered surfaces / Ni / Au

Rework technology

Diameters: 0,5 / 0,8 / 1,0 / 1,5 mm
 Spools: 250 g / 500 g / 1 kg
 Package unit: 6 kg = 24 spools 250 g
 12 spools 500 g
 6 spools 1 kg